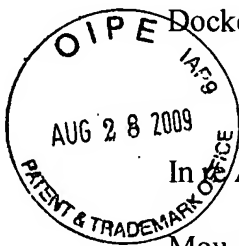


08-31-09

FW



Docket No.: 085027-0058

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Application of

Mou-Shiung Lin, et al.

Application No.: 10/055,560

Filed: January 22, 2002

For: INTEGRATED CHIP PACKAGE STRUCTURE USING METAL SUBSTRATE AND  
METHOD OF MANUFACTURING THE SAME

: Customer Number: 89518  
:  
: Confirmation Number: 6103  
:  
: Group Art Unit: 2813  
:  
: Examiner: MITCHELL, JAMES M.  
:

**TRANSMITTAL OF POWER OF ATTORNEY**


Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Transmitted herewith is a Power Of Attorney to Prosecute Applications Before the  
USPTO, together with a Statement Under 37 CFR 3.73(b), which revokes all previous powers of  
attorney given in the above-identified application and associates the application with Customer  
Number 89518.

Respectfully submitted,

McDERMOTT WILL & EMERY LLP

  
Dennis A. Duchene

Registration No. 40,595

11682 El Camino Real, Suite 400  
San Diego, CA 92130  
Phone: 858.720.3300 DAD:MWE  
Facsimile: 858.720.7800  
**Date: August 28, 2009**

**Please recognize our Customer No. 89518  
as our correspondence address.**